

## Features

- High Voltage, Higher Current Diodes in Small Form Factor
- Utilizes DTI's High Performance XOE™ Technology
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

## Specifications<sup>1</sup>

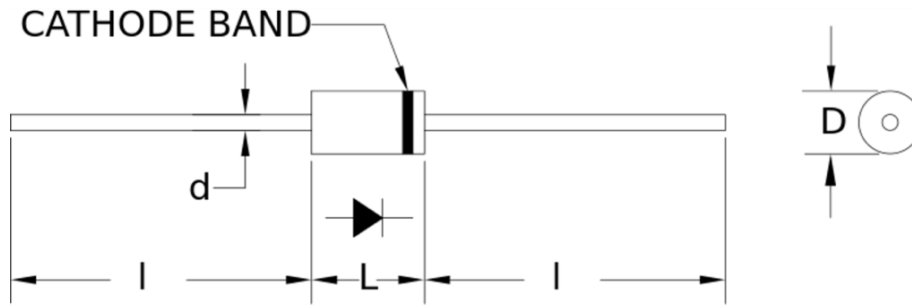
Part Number	V <sub>RRM</sub> V	I <sub>FAVM1</sub> mA	I <sub>FAVM2</sub> mA	V <sub>F</sub> V	I <sub>R</sub> μA	I <sub>FSM</sub> A	C <sub>J</sub> <sup>2</sup> pF	T <sub>RR</sub> nS	R <sub>θJA</sub> °C/W	E <sub>RSM</sub> mJ	L in.	D in.	d in.	I in.
XGA02	2000	340	170	5.4	0.2	5	2.9	70	112	40	0.195	0.08	0.02	1.0
XGA03	3000	260	130	7.5	0.2	5	2.8	70	112	40	0.195	0.08	0.02	1.0
XGA04	4000	220	110	10.4	0.2	5	3.7	70	112	40	0.195	0.08	0.02	1.0
XGA05	5000	180	90	11.3	0.2	5	2.6	70	112	40	0.195	0.08	0.02	1.0
XGA06	6000	160	80	13.3	0.2	5	2.4	70	112	50	0.195	0.08	0.02	1.0
XGA08	8000	130	65	15.9	0.2	5	1.5	70	112	70	0.195	0.08	0.02	1.0
XGA10	10000	100	50	18.0	0.2	5	1.4	70	112	70	0.195	0.08	0.02	1.0

Temperature °C	
Operating Temperature	-55 to 125
Storage Temperature	-55 to 175
Maximum Junction Temperature	125

<sup>1</sup>25°C ambient temperature unless stated otherwise.

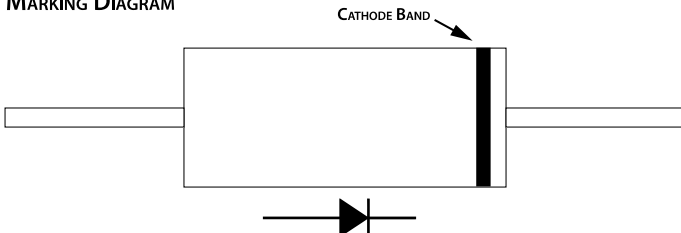
<sup>2</sup>Check Specification Definitions for conditions details.

## Drawings

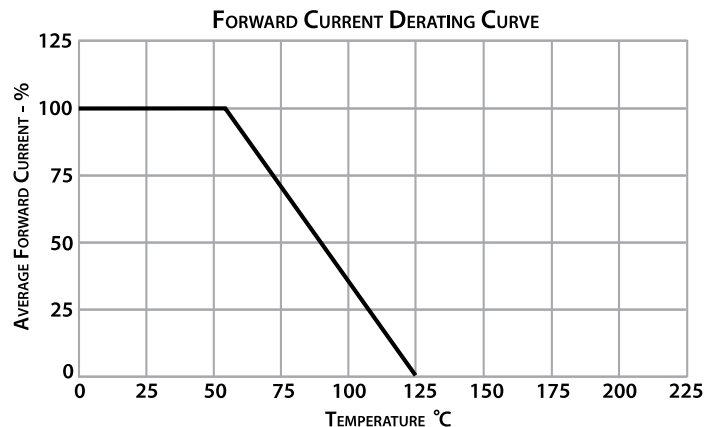


Dimensions in inches, tolerances ±0.020 except as noted

### MARKING DIAGRAM

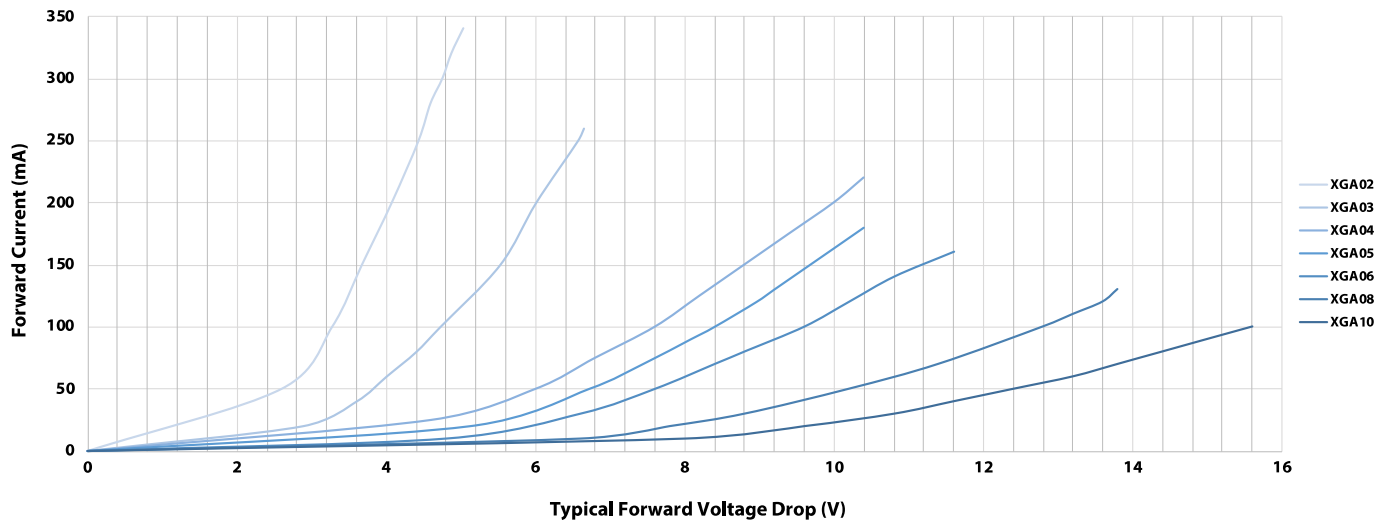


MARKING TYPE: RED, INKJET  
(MARKINGS WILL WRAP ENTIRE BODY OF DIODE AND ARE SUBJECT TO MINOR CHANGES)



# XGA SERIES

Forward Current vs. Typical Forward Voltage Drop,  $T_A = 25^\circ\text{C}$   
XGA Series



## Specification Definitions

Specifications		Conditions
$V_{RRM}$	Maximum Repetitive Reverse Voltage	-
$I_{FAVM1}$	Maximum Average Forward Current	At $T_A = 55^\circ\text{C}$ , in Oil
$I_{FAVM2}$	Maximum Average Forward Current	At $T_A = 55^\circ\text{C}$
$V_F$	Maximum Forward Voltage Drop	At $I_{FAVM1}$ , $t_{PW} = 100\mu\text{sec}$
$I_R$	Maximum Leakage Current	At $V_{RRM}$
$I_{FSM}$	Maximum Surge Current	At 8.3mS, Single Half Sine
$C_J$	Typical Junction Capacitance	At $V_R = 4\text{VDC}$ , $f = 1\text{MHz}$ (XGA02, XGA03) At $V_R = 0\text{VDC}$ , $f = 1\text{MHz}$ (All other models)
$T_{RR}$	Maximum Reverse Recovery Time	$I_F = 0.5 I_{FAVM1}$ ; $I_R = -I_{FAVM1}$ ; $I_{RR} = -0.25 I_{FAVM1}$
$R_{\theta JA}$	Typical Thermal Resistance	Junction to Ambient, in Air
$E_{RSM}$	Maximum Reverse Energy Withstand	-

Note: Specifications subject to change without notice. Photo is representation only.

